



June 11, 2007

To Whom It May Concern,

Savi Technology will change construction of our product referred to in the attached test report because of process changes being made to the chip used in the RF circuit manufactured by Infineon. The chip is now made on 8" wafers and uses AlCu metallization which improves the wiring to the ESD protection devices. Previously the chip was made on 6" wafers and used AlSiCu metallizations.

No other changes have been made to the product design or software. This change will be incorporated in all new build after authorization has been obtained.

Sincerely,

A handwritten signature in black ink, appearing to read "E. Schlindwein".

**Eugene Schlindwein
Compliance Engineer
Savi Technology**